

Electronic Acknowledgement Receipt

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First Named Inventor:	Isaiah O. Oladeji
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1	Supplemental Appeal Brief	CorrectedAppealBrief.pdf	1510912	no	31

Warnings:		
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<p>National Stage of an International Application under 35 U.S.C. 371 If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p>		